

## DESCRIPTION

The MXN8250 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. It can be used in a wide variety of applications. It is ESD protected.

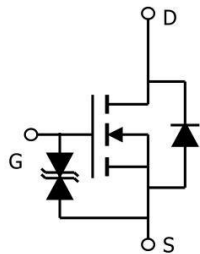
## GENERAL FEATURES

- $V_{DS}=18V, I_D=50A$   
 $R_{DS(ON)}(Typ.)=7m\Omega @ V_{GS}=1.8V$   
 $R_{DS(ON)}(Typ.)=4.7m\Omega @ V_{GS}=2.5V$   
 $R_{DS(ON)}(Typ.)=3.5m\Omega @ V_{GS}=4.5V$
- High Power and current handling capability
- Lead free product is acquired
- Surface Mount Package

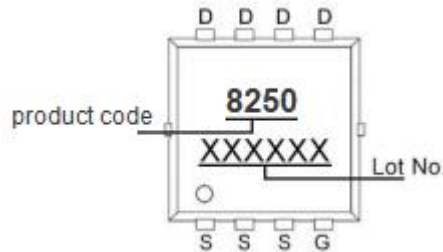
## APPLICATION

- PWM applications
- Load switch
- Power management
- Battery Protection

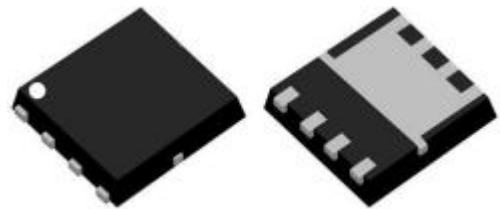
## PINOUT



Schematic diagram



Marking and pin Assignment



PDFN3.3x3.3-8L top & bottom view

## ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MXN8250	-55°C to 150°C	PDFN3.3x3.3-8L	3000

## ABSOLUTE MAXIMUM RATINGS ( $T_C=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	18	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current-Continuous	$I_D$	50	A
Drain Current-Continuous ( $T_C=100^\circ C$ )	$I_D$	40	A
Pulsed Drain Current <sup>(Note1)</sup>	$I_{DM}$	200	A
Maximum Power Dissipation	$P_D$	36	W
Avalanche Current	$I_{AS}$	40	A
Avalanche Energy ( $L=0.1mH$ )	$E_{AS}$	80	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$

## THERMAL RESISTANCE

Thermal Resistance, Junction-to-Ambient <sup>(Note2)</sup>	$R_{\theta JC}$	3.5	$^\circ C/W$
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Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.


**ELECTRICAL CHARACTERISTICS** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
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**Off Characteristics**

Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	-	18	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=16V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 10V, V_{DS}=0V$	-	-	$\pm 10$	$\mu A$

**On Characteristics** (Note2)

Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.45	0.7	1.0	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=1.8V, I_D=2A$	-	7	10	$m\Omega$
		$V_{GS}=2.5V, I_D=7A$	-	4.7	6	$m\Omega$
		$V_{GS}=4.5V, I_D=15A$	-	3.5	4.2	$m\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=5V, I_D=20A$	-	100	-	S

**Dynamic Characteristics** (Note3)

Input Capacitance	$C_{iss}$	$V_{DS}=10V, V_{GS}=0V,$ $F=1.0MHz$	-	2300	-	$pF$
Output Capacitance	$C_{oss}$		-	560	-	$pF$
Reverse Transfer Capacitance	$C_{rss}$		-	500	-	$pF$
Gate Resistance	$R_g$	$V_{DS}=10V, V_{GS}=0V,$ $F=1.0MHz$	-	0.5	-	$K\Omega$

**Switching Characteristics**

Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=10V, R_L=1\Omega,$ $V_{GS}=4.5V, R_G=3\Omega$	-	7.5	-	$nS$
Turn-on Rise Time	$t_r$		-	15	-	$nS$
Turn-Off Delay Time	$t_{d(off)}$		-	72	-	$nS$
Turn-Off Fall Time	$t_f$		-	21	-	$nS$
Total Gate Charge	$Q_g$	$V_{DS}=10V, I_D=20A,$ $V_{GS}=4.5V$	-	36	-	$nC$
Gate-Source Charge	$Q_{gs}$		-	5.6	-	$nC$
Gate-Drain Charge	$Q_{gd}$		-	11	-	$nC$

**Drain-Source Diode Characteristics**

Diode Forward Voltage (Note2)	$V_{SD}$	$V_{GS}=0V, I_S=1A$	-	-	1.2	V
Diode Forward Current (Note1)	$I_S$		-	-	20	A

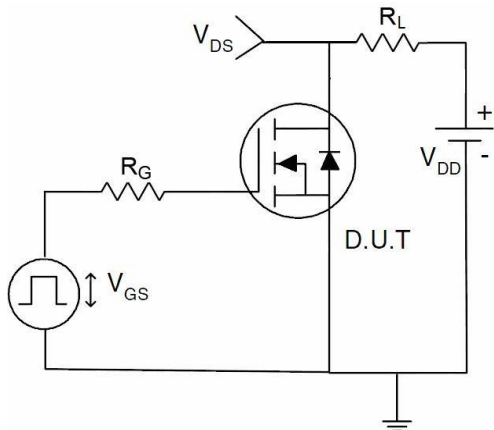
Note 1. Surface Mounted on FR4 Board,  $t \leq 10$  sec.

Note 2. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .

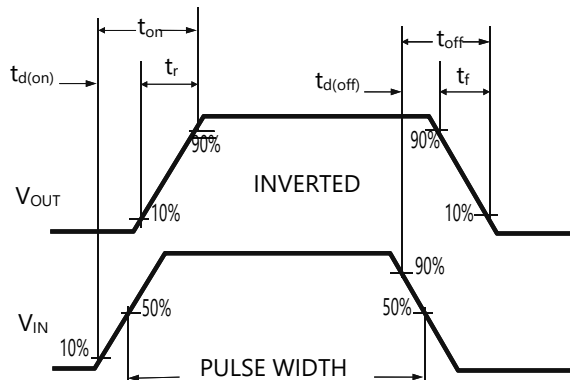
Note 3. Guaranteed by design, not subject to product.

**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

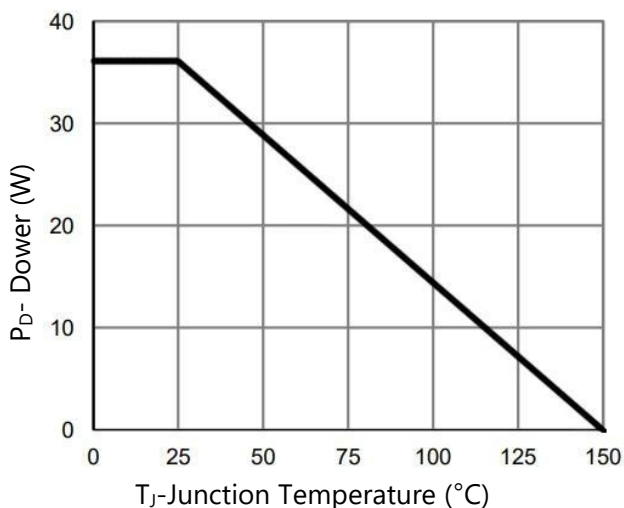
**Figure 1. Switching Test Circuit**



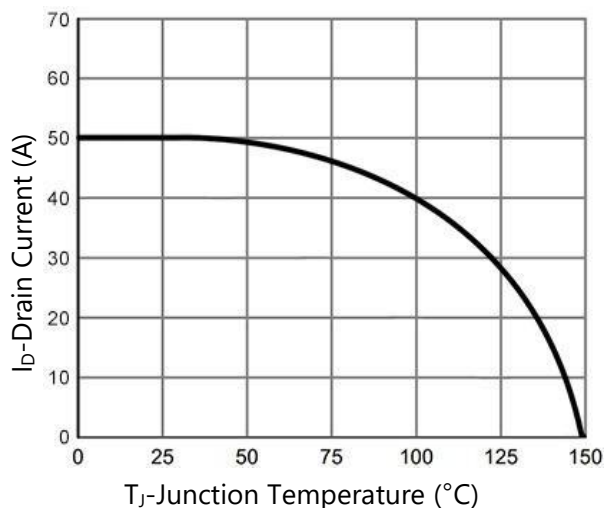
**Figure 2. Switching Waveform**



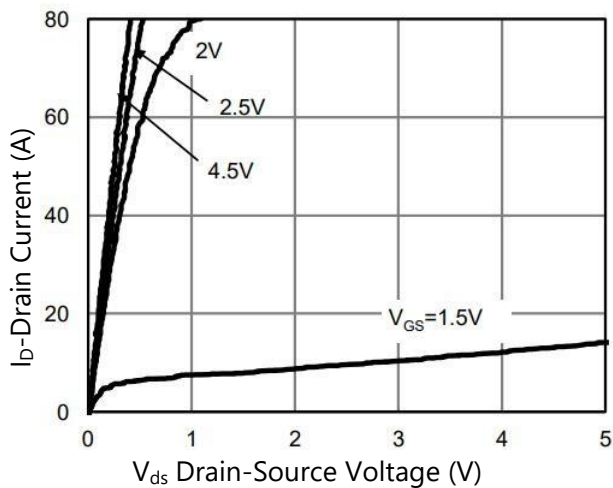
**Figure 3. Power Dissipation**



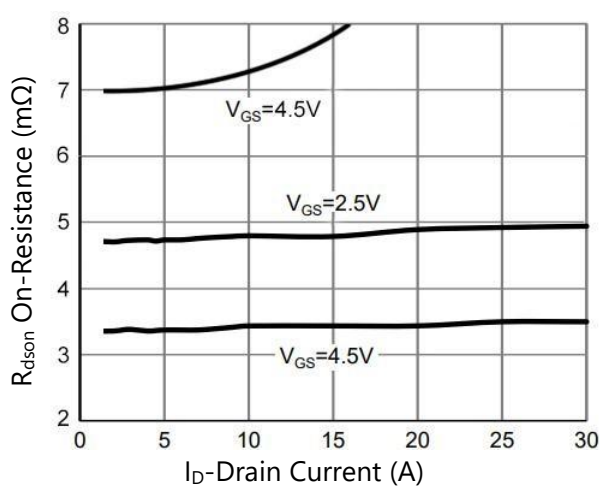
**Figure 4. Drain Current**



**Figure 5. Output Characteristics**



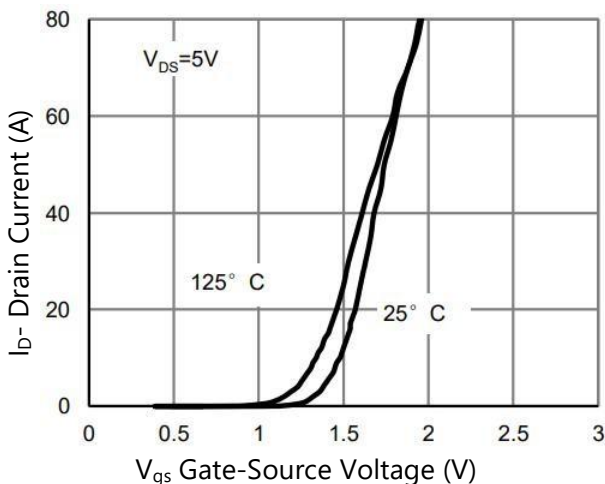
**Figure 6. R<sub>dson</sub> vs Drain Current**



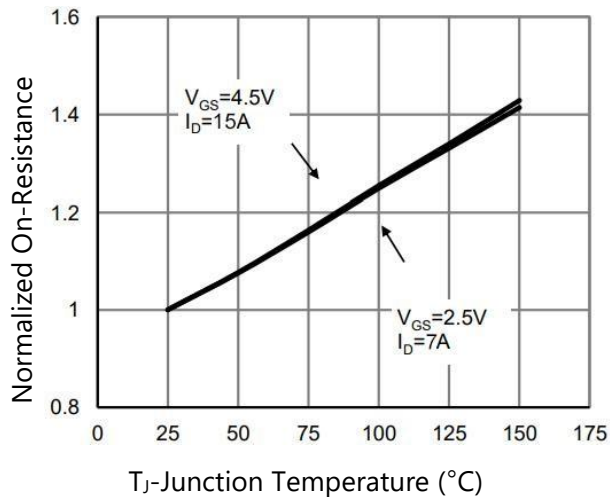


**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

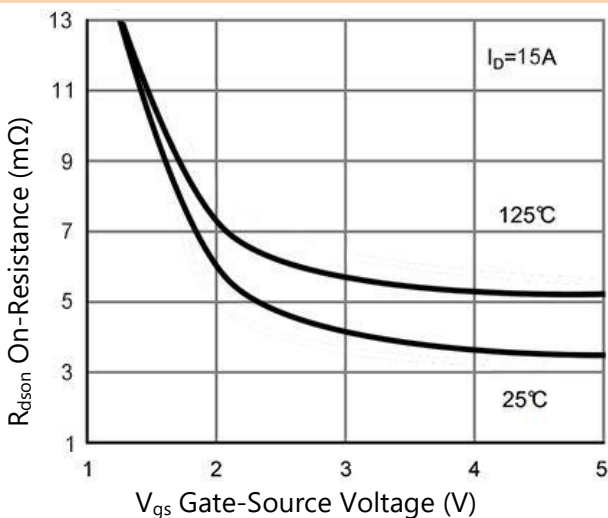
**Figure 7. Transfer Characteristics**



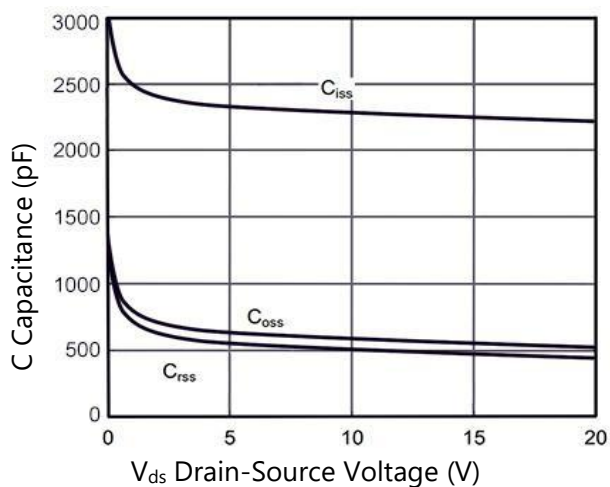
**Figure 8. R<sub>dson</sub> vs Junction Temperature**



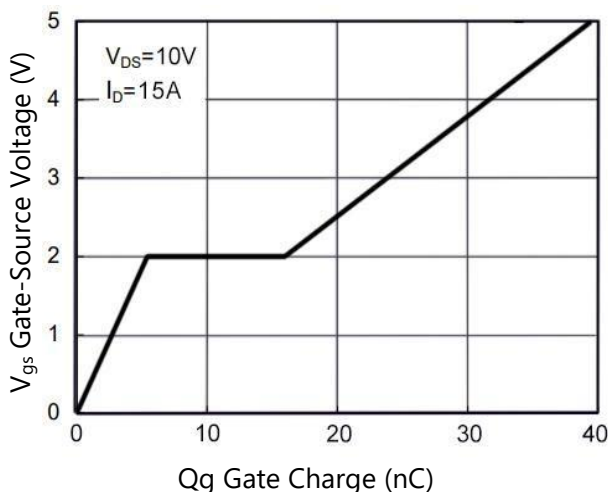
**Figure 9. R<sub>dson</sub> vs V<sub>gs</sub>**



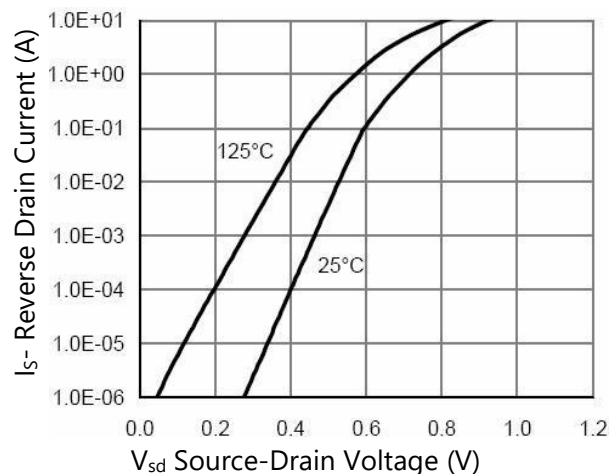
**Figure 10. Capacitance vs V<sub>DS</sub>**



**Figure 11. Gate Charge**

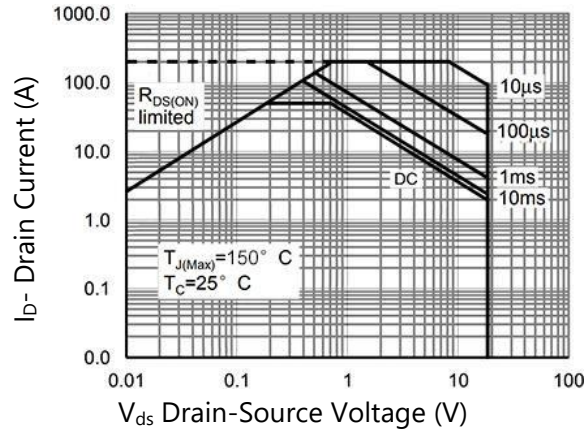


**Figure 12. Source- Drain Diode Forward**

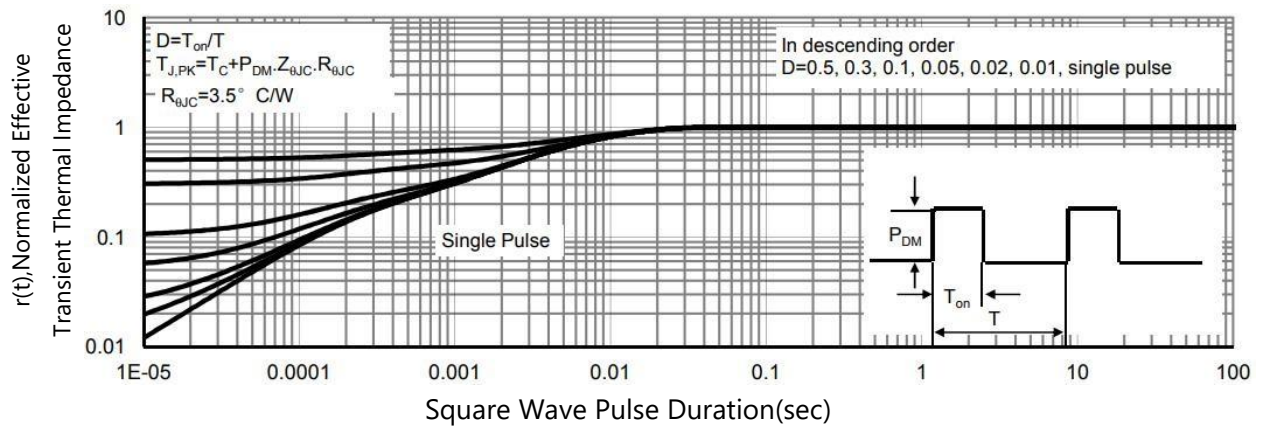


**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

**Figure 13. Safe Operation Area**

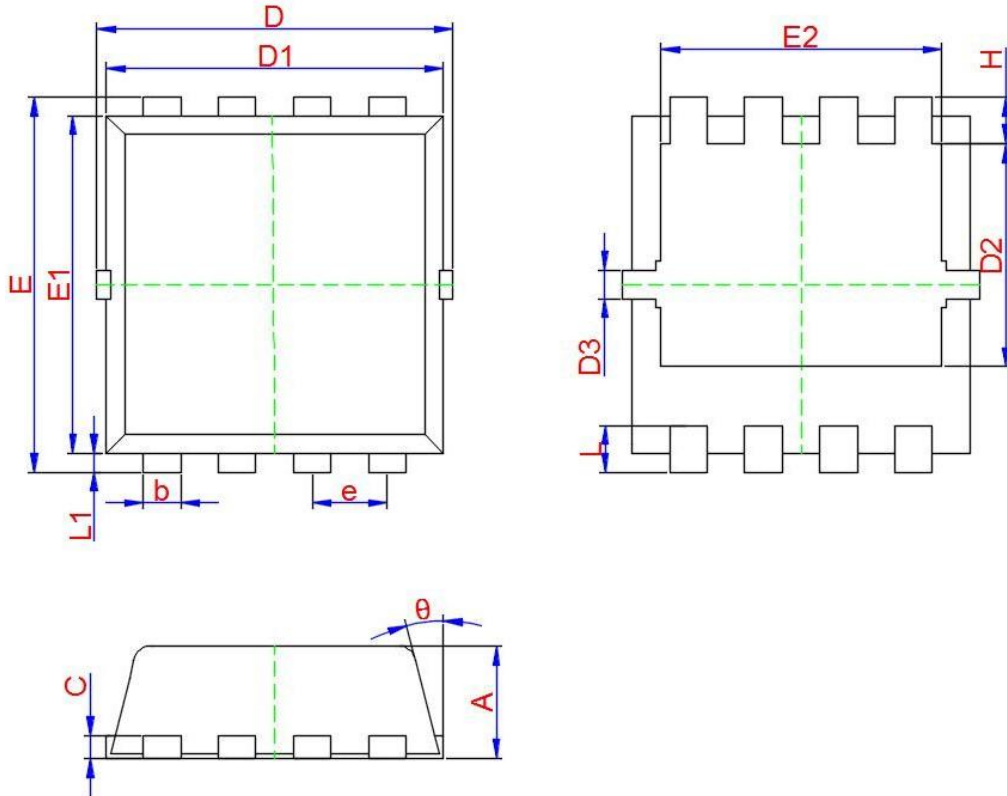


**Figure 14. Normalized Maximum Transient Thermal Impedance**



**PACKAGE INFORMATION**

PDFN3.3x3.3-8L



Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.700	0.775	0.850
b	0.250	0.300	0.350
c	0.100	0.150	0.250
D	3.150	3.300	3.400
D1	2.950	3.100	3.200
D2	1.700	1.800	1.930
D3	-	0.130	-
E	3.050	3.250	3.350
E1	2.950	3.150	3.200
E2	2.300	2.400	2.550
e	0.650 TYP.		
H	0.330	0.430	0.530
L	0.300	0.400	0.500
L1	0.080	0.130	0.180
θ	-	10°	-